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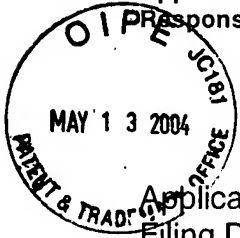
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Application Serial No. 10/004,172
Response to December 16, 2003 Final OA

MI22-1839



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 10/004,172
Filing Date October 9, 2001
Inventor Warren M. Farnworth et al.
Assignee Micron Technology, Inc.
Group Art Unit 3729
Examiner A.D. Tugbang
Attorney's Docket No. MI22-1839
Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate, and Bonding
Frames

RESPONSE TO DECEMBER 16, 2003 FINAL OFFICE ACTION
PURSUANT TO 37 C.F.R. §1.116

To: Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

From: D. Brent Kenady
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Spokane, WA 99201-3828

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MAY 20 2004

TECHNOLOGY CENTER R3700

Responsive to the Final Office Action dated December 16, 2003, Applicant
amends and remarks as follows:

AMENDMENTS